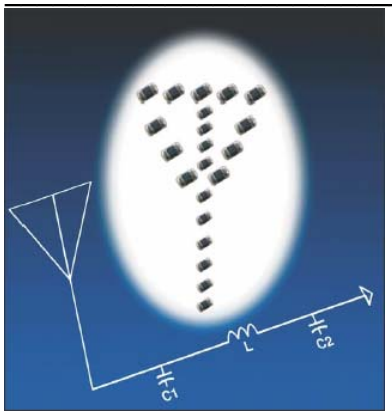
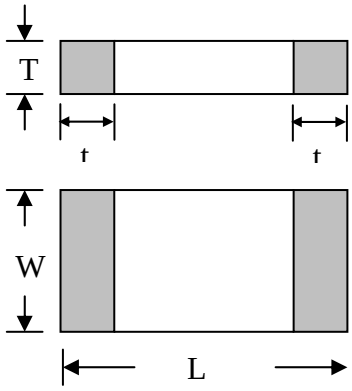
VCH4AG100R8MATWA



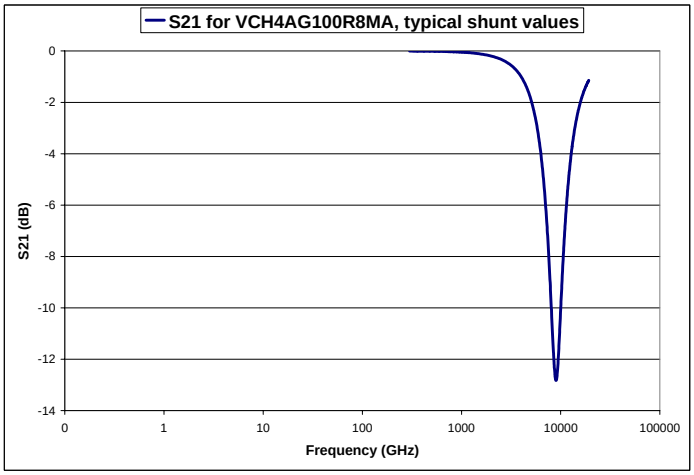


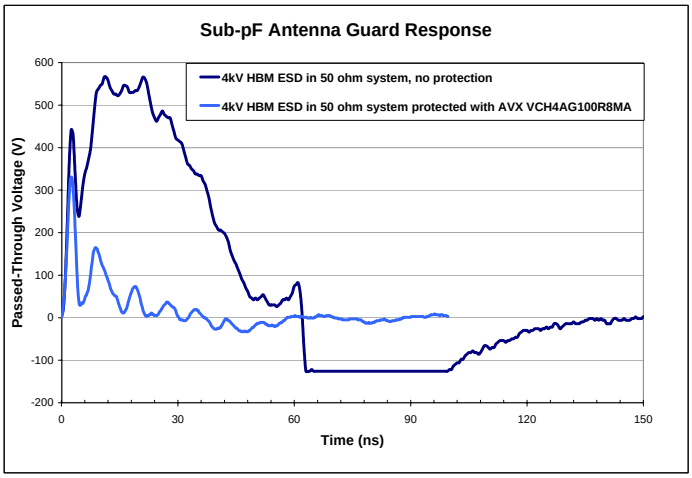
Size (EIA)		0402
Length (L)	mm (in)	1.00 ±0.10 (0.040 ± 0.004)
Width (W)	mm (in)	0.50 ±0.10 (0.020 ±0.004)
Max Thickness (T)	mm (in)	0.35 (0.014)
Terminal (t)	mm (in)	0.25±0.15 (0.010±0.006)

VCH4	AG	10	0R8	M	A	T	W	A
Varistor Chip Chip Size Thin 0402	Varistor Series AntennaGuard	Working Voltage 10 = 10V	Capacitance Value 0R8 = 0.8pf	Tolerance M = ±20%	N/A	Termination T = Ni/Sn Alloy	Reel Size W = 7”	Reel Qty A = 4k

AVX Part Number	V_W(DC)	V_B	I_L	Cap	Freq	Case Size
VCH4AG100R8MA	≤10	125	<10 nA	0.8	M	0402

V_W(DC) DC Working Voltage [V]
V_B Typical Breakdown Votage [V @ $1mA_{DC}$]
I_L Typical leakage current at the working voltage
Cap Typical capacitance [pF] @ frequency specified and $0.5V_{RMS}$
Freq Frequency at which capacitance is measured [M = 1MHz]





Parameter/Test	Requirement	Test method
Operating Range	-55°C to +125° C	
Appearance/Dimensions	No visible damage Dimensions: see par. 6	Visual examination at 10% magnification Dimensions verification by class2 caliper
Solderability	The dipped surface shall be at least 95% covered with a new smooth solder coating.	Soak in eutectic solder bath of temperature at 230+/-5°C for 5sec.
Solder Heat Resistance	No mechanical damage. Forward Breakdown voltage change shall not be more than ± 10%	a. Read forward breakdown voltage. b. Soak in eutectic solder bath of temperature at 260+/-5°C. for 10+/-1sec. c. Natural cool down to +25°C d. Read forward breakdown voltage after 24+/-2 hours.
ESD	IL @ RV <100nA	a. Read IL b. 1k pulses @ 8kV contact (8 X 20uS waveform) c. Read IL
Life Test	Forward breakdown voltage change shall not be more than ± 10%	a. Read forward breakdown voltage. b. Apply 100% of working voltage at test temperature of 125+/-4°C for 1,000+48/-0hours. c. Read forward breakdown voltage after 24+/-2 hours conditioning at 25+/-5°C
Termination Strength	All components must stay in place.	a. Solder components onto substrate. b. Apply 500 grams lateral force across the body of the component.
Thermal Shock	Forward breakdown voltage change shall not be more than ± 10%	Step 1: -55°C ± 2°C for 30 ± 3 min Step 2: Room temp for ≤ 3 min Step 3: +125°C ± 2°C for 30 ± 3 min Step 4: Room temp for ≤ 3 min Repeat for 100 cycles and measure after 24 hours at room temperature